



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-08-21
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CDK7*0084BG6	A	BO2A	2018-08-21
	Amount	UoM	Unit type	ST ECOPACK Grade
	130	mg	Each	ECOPACK® 3
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	250	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6x3.9x1.52	14	gull wing	
Comment	K7 SO 14 .15 TO JEDEC MS-01; MDF valid for TL084IDT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
;				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CDK7*0084BG6				6000001.0	999999.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.405	mg	supplier	die	Silicon (Si)	7440-21-3		2.362	mg	982121	18169
				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	8316	154
				supplier	Passivation	Silicon Nitride	12033-89-5		0.010	mg	4158	77
				supplier	Passivation	Silicon Oxide	7631-86-9		0.013	mg	5405	100
				supplier	alloy	Copper (Cu)	7440-50-8		33.885	mg	930549	260654
Leadframe	M-004 Copper and its alloys	36.414	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.797	mg	21887	6131
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.048	mg	1318	369
				supplier	alloy	Zinc (Zn)	7440-66-6		0.042	mg	1153	323
				supplier	metallization	Silver (Ag)	7440-22-4		1.642	mg	45093	12631
				supplier	glue	Silver (Ag)	7440-22-4		0.767	mg	876571	5900
Die attach	M-015 Other organic materials	0.875	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.044	mg	50286	338
				supplier	glue	Acrylate resin	5888-33-5		0.044	mg	50286	338
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.018	mg	20571	138
				supplier	glue	Epoxyoctahydroxyethyltrimethoxysilane	3388-04-3		0.001	mg	1143	8
				supplier	glue	Tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1143	8
Bonding wires	M-011 Other inorganic materials	0.082	mg	supplier	wire	Copper (Cu)	7440-50-8		0.082	mg	1000000	631
Encapsulation	M-015 Other organic materials	89.324	mg	supplier	mold compound	Silica, vitreous	60676-86-0		77.355	mg	866005	595038
				supplier	mold compound	Epoxy Resin	85954-11-6		6.699	mg	74997	51531
				supplier	mold compound	Phenol Resin	26834-02-6		4.466	mg	49998	34354
				supplier	mold compound	Carbon black	1333-86-4		0.447	mg	5004	3438
				supplier	mold compound	Bismuth compound	7440-69-9		0.357	mg	3997	2746
connections coating	Solder	0.900	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.900	mg	1000000	6923